



**Please note that Cypress is an Infineon Technologies Company.**

The document following this cover page is marked as “Cypress” document as this is the company that originally developed the product. Please note that Infineon will continue to offer the product to new and existing customers as part of the Infineon product portfolio.

**Continuity of document content**

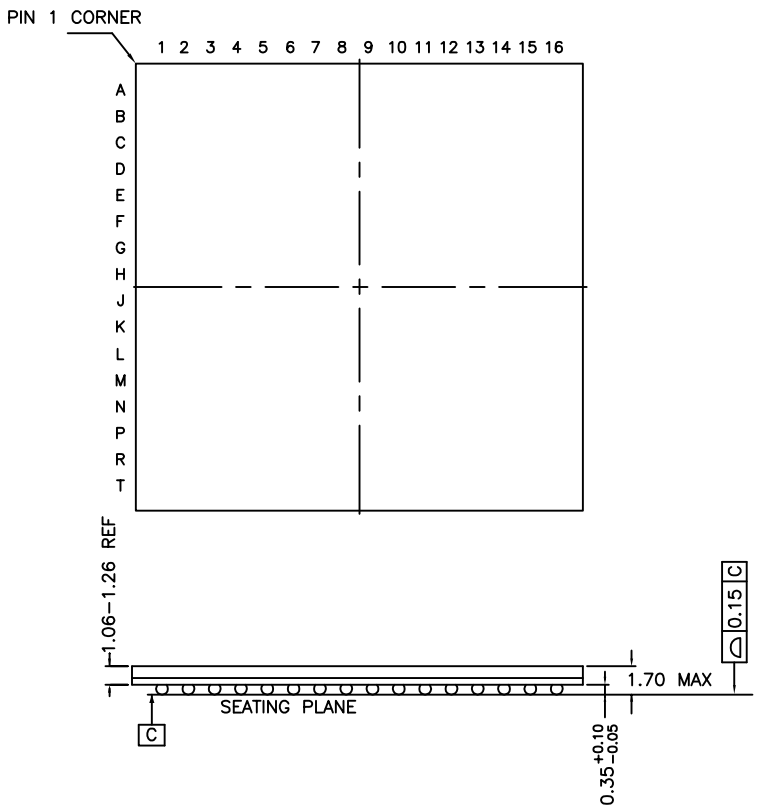
The fact that Infineon offers the following product as part of the Infineon product portfolio does not lead to any changes to this document. Future revisions will occur when appropriate, and any changes will be set out on the document history page.

**Continuity of ordering part numbers**

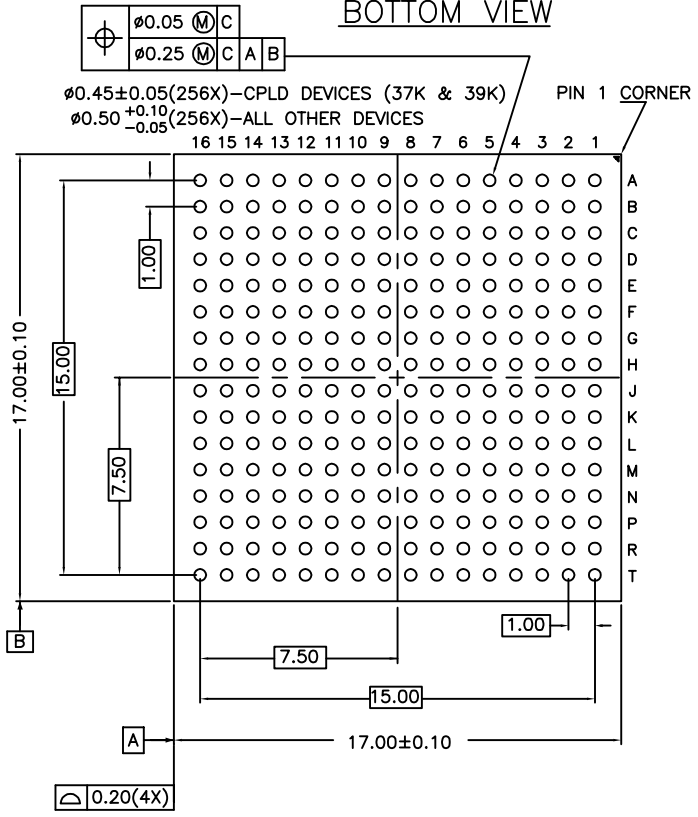
Infineon continues to support existing part numbers. Please continue to use the ordering part numbers listed in the datasheet for ordering.

REVISIONS						
PAGE	ZONE	REV	ECN	DESCRIPTION	DATE	APPROVED
1	-	**	61985	NEW RELEASE	04/29/99	N/A
1	-	*A	100320	CHG. PKG. DIM. THICKNESS TO DIM. TABLE CHG. TITLE	05/25/00	N/A
1	-	*B	106855	CHG. DIM ON BALL HEIGHT, LEAD COPLANARITY & FLATNESS TOLERANCE	05/07/01	N/A
1	-	*C	113921	CHG. DIM. ON BALL HEIGHT/ADD MOLD CAP DIM./ADD SUBSTRATE DIM.	03/13/02	N/A
1	-	*D	128698	ADD NEW BALL SIZE/ADD JEDEC NO./CHG. TOLERANCE OF BALL HEIGHT.	07/23/03	N/A
1	-	*E	129165	CHG. DIM A FROM 1.6 MAX. TO 1.7 MAX.	08/19/03	N/A
1	-	*F	130445	CHG. TOL. OF BALL DIA. OF ALL OTHER DEVICES	10/13/03	N/A
1	-	*G	2655389	Revise pkg height to one dimension 1.7 MAX. Call out body thickness, 1.06-1.26 REF.	02/06/09	N/A
1	-	*H	2820579	Changed template and Title from 256 FBGA 17x17 PACKAGE OUTLINE to PACKAGE OUTLINE, 256L FBGA 17X17X1.7 MM BB256/BW0BD.	12/09/09	QAD
1	-	*I	3376715	Update spec for sunset review, no changed	09/20/11	QAD
1	-	*J	4713447	Sunset review, no change.	04/07/15	QAD

TOP VIEW



BOTTOM VIEW



UNLESS OTHERWISE SPECIFIED ALL DIMENSIONS ARE IN MILLIMETERS STANDARD TOLERANCES ON: DECIMALS .XX ± 0.05 .XXX ± .XXXX ± ANGLES ± 1°	DESIGNED BY MLA	DATE 02/06/09	
	DRAWN BY MLA	DATE 02/06/09	
	CHECKED BY TSV	DATE 12/09/09	
	APPROVED BY QAD	DATE 12/09/09	
MATERIAL N/A	APPROVED BY JGUA	DATE 12/09/09	TITLE PACKAGE OUTLINE, 256L FBGA 17X17X1.7 MM BB256/BW0BD
FINISH N/A	APPROVED BY N/A	DATE N/A	SIZE A PART NO. BB256/BW0BD DWG NO. 51-85108 REV *J
SCALED TO FIT		N/A	SHEET 1 OF 1

REFERENCE JEDEC MO-192 PACKAGE WEIGHT - 0.95gr

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